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(54) Title: COMPOSITION FOR FORMING A COPPER-CONTAINING INTERLAYER COMPRISING INTERNAL PORES

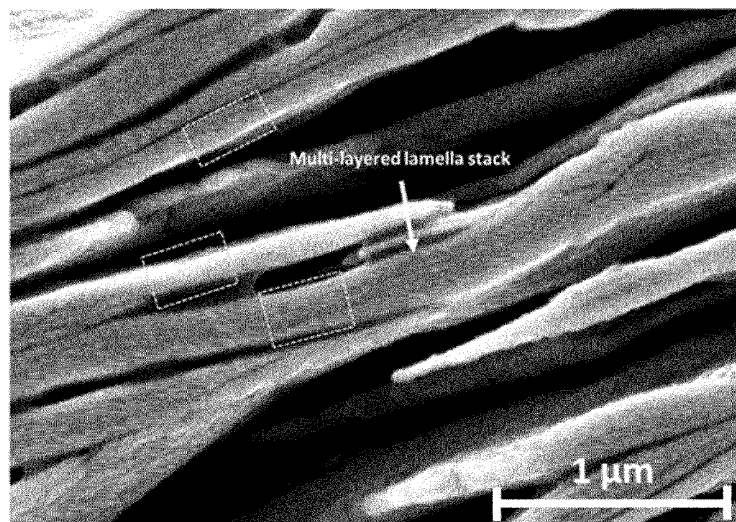


Fig. 2

(57) Abstract: The invention concerns a composition for forming a copper-containing interlayer between a first solid substrate and a second solid substrate which composition comprises or consists of the following components: An organic binder and flakes of copper or a copper alloy, wherein the flakes comprise internal pores, wherein the flakes have a multi-layer lamellar structure.



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